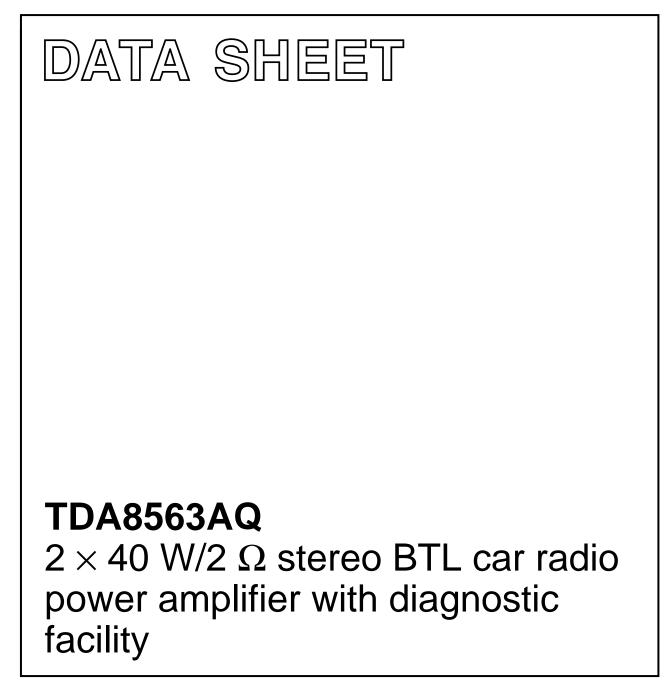
INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC01 1997 Feb 20



Product specification

2×40 W/2 Ω stereo BTL car radio power amplifier with diagnostic facility

FEATURES

- Requires very few external components
- High output power
- 4 Ω and 2 Ω load impedance
- Low output offset voltage
- Fixed gain
- Diagnostic facility (distortion, short-circuit and temperature detection)
- Good ripple rejection
- Mode select switch (operating, mute and standby)
- Load dump protection
- Short-circuit safe to ground, to V_{P} and across the load
- Low power dissipation in any short-circuit condition

- Thermally protected
- Reverse polarity safe
- Electrostatic discharge protection
- No switch-on/switch-off plop
- Flexible leads
- Low thermal resistance.

GENERAL DESCRIPTION

The TDA8563AQ is an integrated class-B output amplifier in a 13-lead single-in-line (SIL) power package. It contains 2×40 W/2 Ω amplifiers in BTL configuration.

The device is primarily developed for car radio applications.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	operating supply voltage		6.0	14.4	18	V
I _{ORM}	repetitive peak output current		-	-	7.5	A
I _{q(tot)}	total quiescent current		-	115	-	mA
I _{sb}	standby current		-	0.1	100	μA
I _{sw}	switch-on current		-	_	40	μA
Z _I	input impedance		25	30	-	kΩ
Po	output power	$R_L = 4 \Omega$; THD = 10%	-	25	-	W
		$R_L = 2 \Omega$; THD = 10%	-	40	_	W
SVRR	supply voltage ripple rejection	$R_s = 0 \Omega$	-	60	-	dB
α _{cs}	channel separation	$R_s = 10 \text{ k}\Omega$	-	50	-	dB
Gv	closed loop voltage gain		25	26	27	dB
V _{no}	noise output voltage	$R_s = 0 \Omega$	-	_	120	μV
ΔV _O	DC output offset voltage		-	-	150	mV

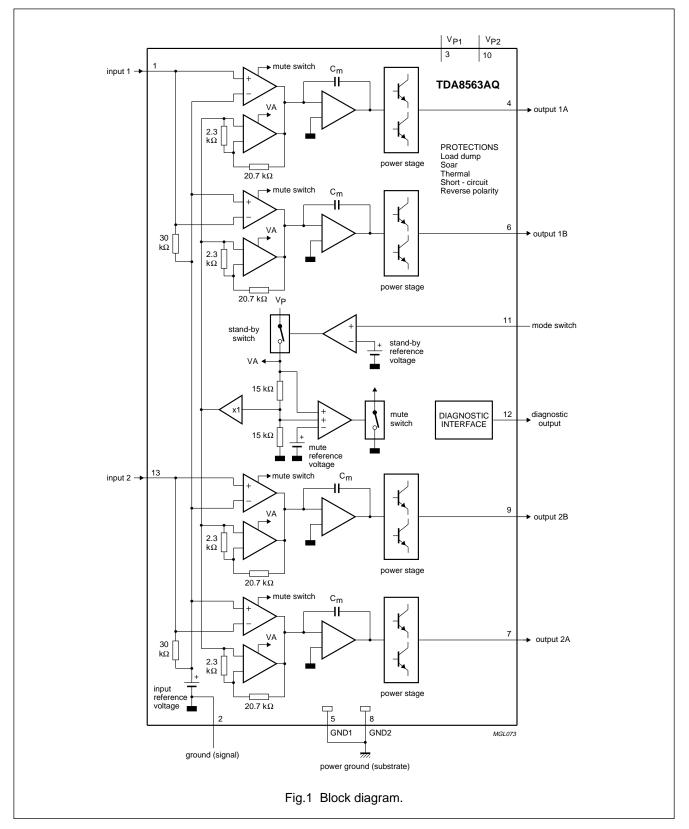
ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
	NAME DESCRIPTION VERSIO				
TDA8563AQ	DBS13P	DBS13P plastic DIL-bent-SIL power package; 13 leads (lead length 12 mm)			

TDA8563AQ

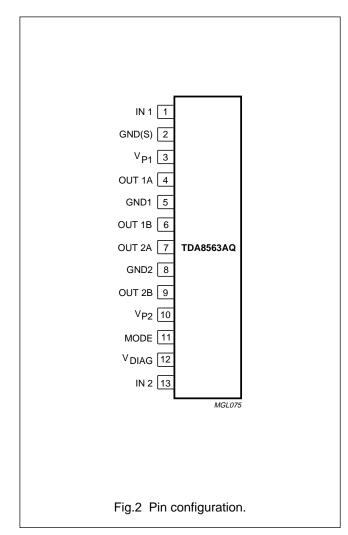
2×40 W/2 Ω stereo BTL car radio power amplifier with diagnostic facility

BLOCK DIAGRAM



PINNING

SYMBOL	PIN	DESCRIPTION
IN 1	1	input 1
GND(S)	2	signal ground
V _{P1}	3	supply voltage 1
OUT 1A	4	output 1A
GND1	5	power ground 1
OUT 1B	6	output 1B
OUT 2A	7	output 2A
GND2	8	power ground 2
OUT 2B	9	output 2B
V _{P2}	10	supply voltage 2
MODE	11	mode switch input
V _{DIAG}	12	diagnostic output
IN 2	13	input 2



FUNCTIONAL DESCRIPTION

The TDA8563AQ contains two identical amplifiers and can be used for bridge applications. The gain of each amplifier is fixed at 26 dB. Special features of the device are as follows.

Mode select switch (pin 11)

- Standby: low supply current (<100 μA)
- Mute: input signal suppressed
- Operating: normal on condition.

Since this pin has a very low input current (<40 μ A), a low cost supply switch can be applied.

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during \geq 100 ms (charging of the input capacitors at pin 1 and pin 13). During switching from standby to mute, the slope should be at least 18 V/s.

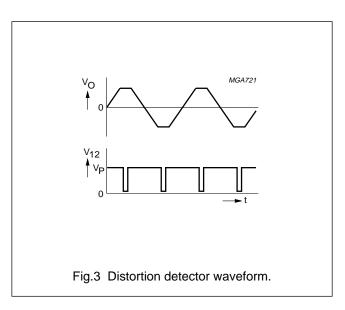
This can be achieved by:

- Microprocessor control
- External timing circuit (see Fig.7).

Diagnostic output (pin 12)

DYNAMIC DISTORTION DETECTOR (DDD)

At the onset of clipping of one or more output stages, the dynamic distortion detector becomes active and pin 12 goes low. This information can be used to drive a sound processor or DC volume control to attenuate the input signal and thus limit the distortion. The output level of pin 12 is independent of the number of channels that are clipping (see Fig.3).



TDA8563AQ

SHORT-CIRCUIT PROTECTION

When a short-circuit occurs at one or more outputs to ground or to the supply voltage, the output stages are switched off until the short-circuit is removed and the device is switched on again, with a delay of approximately 20 ms, after removal of the short-circuit. During this short-circuit condition, pin 12 is continuously low.

When a short-circuit across the load of one or both channels occurs the output stages are switched off during approximately 20 ms. After that time it is checked during approximately 50 μ s to see whether the short-circuit is still present. Due to this duty cycle of 50 μ s/20 ms the average current consumption during this short-circuit condition is very low (approximately 40 mA).

During this short-circuit condition, pin 12 is low for 20 ms and high for 50 μs (see Fig.4).

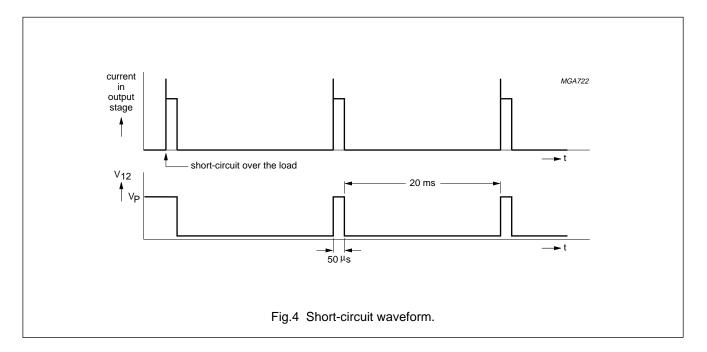
The power dissipation in any short-circuit condition is very low.

TEMPERATURE DETECTION

When the virtual junction temperature $T_{\nu j}$ reaches 150 °C, pin 12 will become continuously low.

OPEN COLLECTOR OUTPUT

Pin 12 is an open collector output, which allows pin 12 of more devices being tied together.



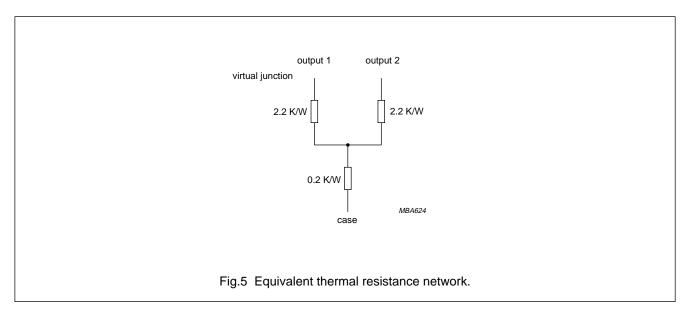
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _P	supply voltage				
	operating		-	18	V
	non-operating		-	30	V
	load dump protection	during 50 ms; $t_r \ge 2.5$ ms	-	45	V
V _{psc}	AC and DC short-circuit safe voltage		-	18	V
V _{pr}	reverse polarity		-	6	V
I _{OSM}	non-repetitive peak output current		-	10	A
I _{ORM}	repetitive peak output current		-	7.5	A
P _{tot}	total power dissipation		-	60	W
T _{stg}	storage temperature		-55	+150	°C
T _{amb}	operating ambient temperature		-40	+85	°C
T _{vj}	virtual junction temperature		-	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient in free air	40	K/W
R _{th j-c}	thermal resistance from junction to case (see Fig.5)	1.3	K/W



TDA8563AQ

DC CHARACTERISTICS

 V_{P} = 14.4 V; T_{amb} = 25 °C; measured in Fig.6; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply			_			
V _P	supply voltage	note 1	6.0	14.4	18	V
lq	quiescent current	$R_L = \infty$	_	115	180	mA
Operating co	ondition					
V ₁₁	mode switch voltage level		8.5	_	VP	V
I ₁₁	mode switch current	V ₁₁ = 14.4 V	_	15	40	μA
Vo	DC output voltage	note 2	_	7.3	-	V
$ \Delta V_{O} $	DC output offset voltage		_	_	150	mV
Mute conditi	on			·		•
V ₁₁	mode switch voltage level		3.3	-	6.4	V
Vo	DC output voltage	note 2	_	7.3	-	V
$ \Delta V_0 $	DC output offset voltage		_	_	150	mV
Standby con	dition					
V ₁₁	mode switch voltage level		0	-	2	V
I _{sb}	standby current		_	0.1	100	μA
Diagnostic o	utput					
V ₁₂	diagnostic output voltage	any short-circuit or clipping	-	_	0.6	V

Notes

1. The circuit is DC adjusted at V_P = 6 to 18 V and AC operating at V_P = 8.5 to 18 V.

2. At 18 V < V_P < 30 V the DC output voltage $\leq \frac{1}{2}$ V_P.

TDA8563AQ

AC CHARACTERISTICS

 V_P = 14.4 V; R_L = 2 Ω ; f = 1 kHz; T_{amb} = 25 °C; measured in Fig.6; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Po	output power	THD = 0.5%	25	30	_	W
		THD = 10%	33	40	_	W
		THD = 30%	45	55	_	W
Po	output power	THD = 0.5%; V _P = 13.2 V	_	25	_	W
		THD = 10%; V _P = 13.2 V	_	35	_	W
THD	total harmonic distortion	$P_o = 1 W$	-	0.1	-	%
		$V_{12} \le 0.6 \text{ V}; \text{ note } 1$	_	2.2	_	%
В	power bandwidth	THD = 0.5%; $P_o = -1 dB$ with respect to 25 W	_	20 to 20000	_	Hz
f _{lr}	low frequency roll-off	at –1 dB; note 2	_	25	_	Hz
f _{hr}	high frequency roll-off	at –1 dB	20	-	_	kHz
G _v	closed loop voltage gain		25	26	27	dB
SVRR	supply voltage ripple rejection					
	on	note 3	50	-	-	dB
	mute	note 3	50	_	-	dB
	standby	note 3	80	_	-	dB
Z _i	input impedance		25	30	38	kΩ
V _{no}	noise output voltage					
	on	note 4	-	85	120	μV
	on	note 5	-	100	-	μV
	mute	note 6	-	60	-	μV
α _{cs}	channel separation	note 7	45	-	_	dB
$ \Delta G_v $	channel unbalance		-	-	1	dB
Vo	output voltage in mute	note 8	_	-	2	mV

Notes

- 1. Dynamic distortion detector active.
- 2. Frequency response externally fixed.
- 3. $V_{ripple} = V_{ripple(max)} = 2 V (p-p); R_s = 0 \Omega.$
- 4. B = 20 Hz to 20 kHz; $R_s = 0 \Omega$.
- 5. B = 20 Hz to 20 kHz; $R_s = 10 \text{ k}\Omega$.
- 6. B = 20 Hz to 20 kHz; independent of R_s .
- 7. $P_o = 25 \text{ W}; R_s = 10 \text{ k}\Omega.$
- 8. $V_i = V_{i(max)} = 1 V (RMS).$

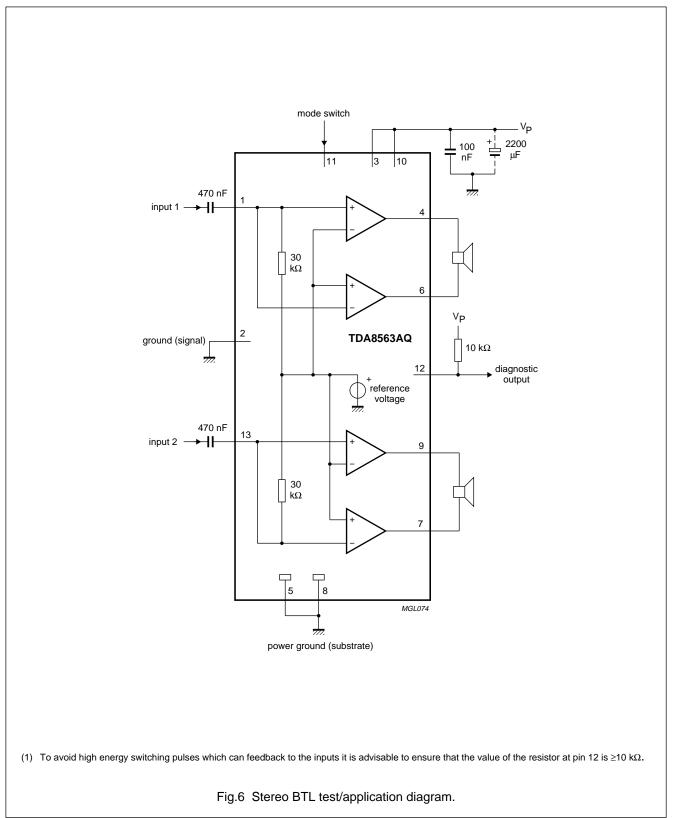
TDA8563AQ

AC CHARACTERISTICS

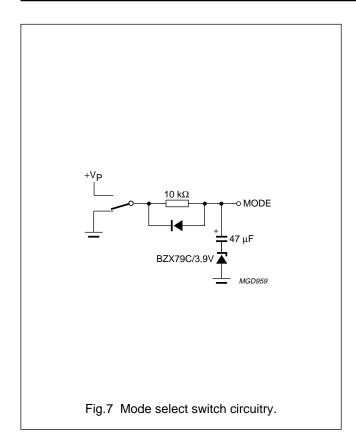
 V_P = 14.4 V; R_L = 4 Ω ; f = 1 kHz; T_{amb} = 25 °C; measured in Fig.6; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Po	output power	THD = 0.5%	16	19	-	W
		THD = 10%	21	25	-	W
		THD = 30%	28	35	-	W
Po	output power	THD = 0.5%; V_P = 13.2 V	-	15	-	W
		THD = 10%; V _P = 13.2 V	—	21	—	W
THD	total harmonic distortion	$P_o = 1 W$	_	0.1	-	%

TEST AND APPLICATION INFORMATION



TDA8563AQ



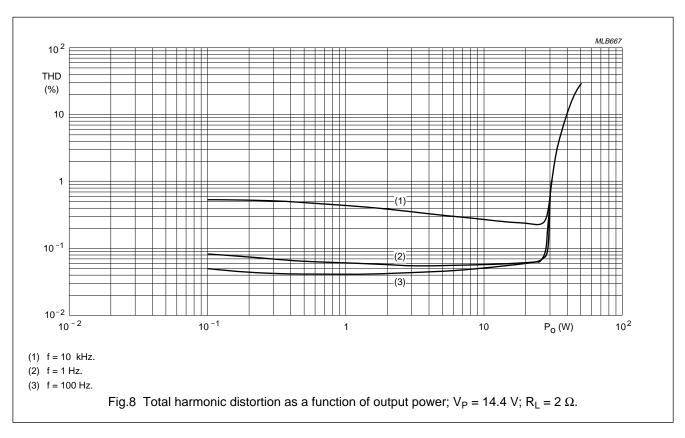
Diagnostic output

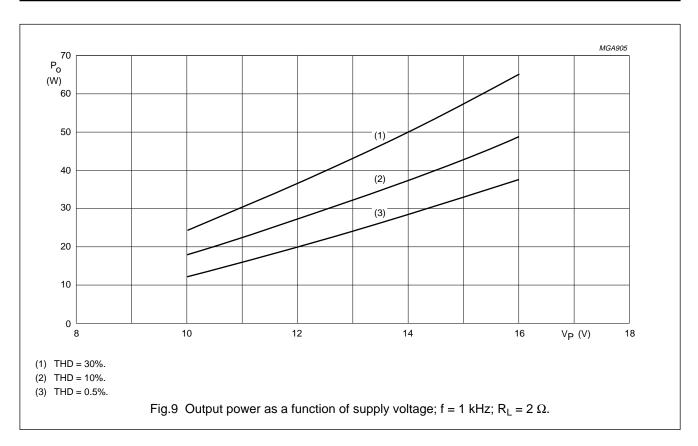
Special care must be taken in the printed-circuit board layout to separate pin 12 from pin 1 and pin 13, to minimize the crosstalk between the diagnostic output and the inputs.

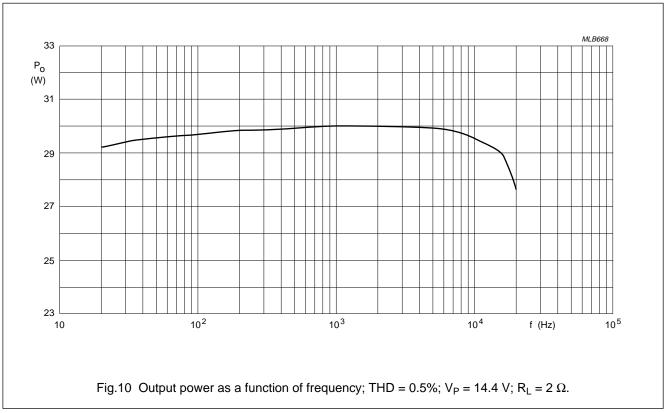
Mode select switch

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during >100 ms (charging of the input capacitors at pin 1 and pin 13).

The circuit in Fig.7 slowly ramps up the voltage at the mode select switch pin when switching on and results in fast muting when switching off.

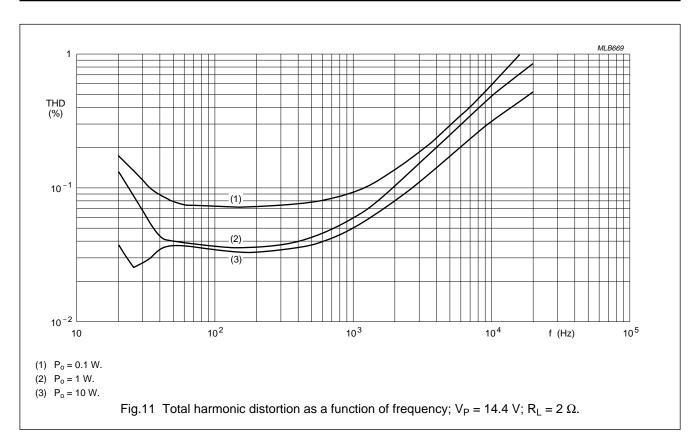


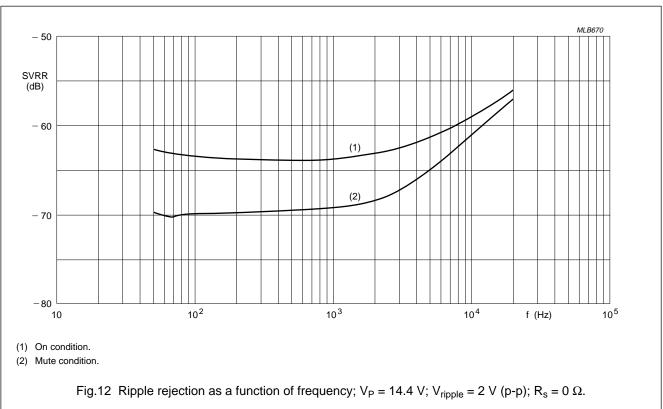




TDA8563AQ

2×40 W/2 Ω stereo BTL car radio power amplifier with diagnostic facility

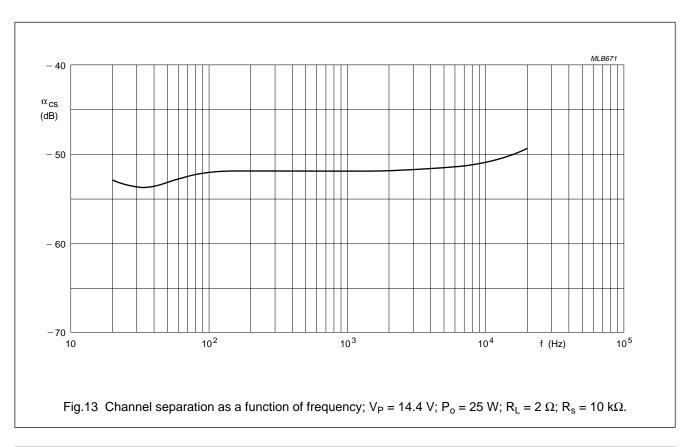


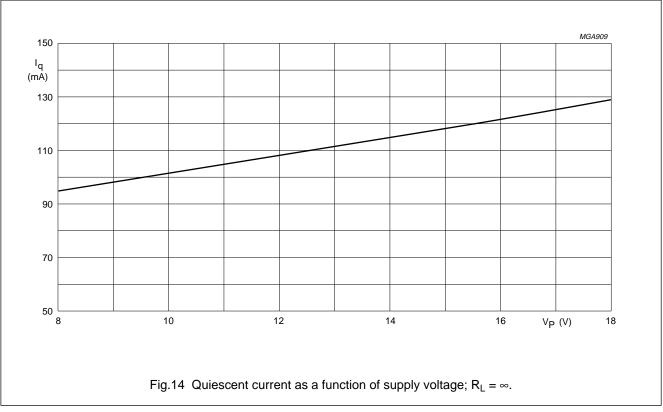


ar radio power

TDA8563AQ

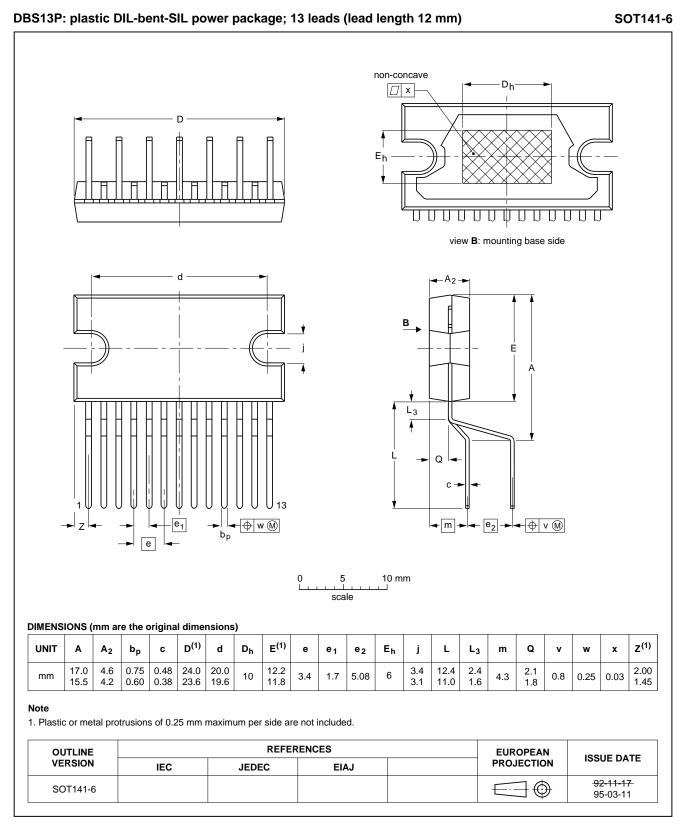
2×40 W/2 Ω stereo BTL car radio power amplifier with diagnostic facility





wer

PACKAGE OUTLINE



SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

NOTES

NOTES

NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113, Tel. +61 2 9805 4455, Fax. +61 2 9805 4466 Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213, Tel. +43 1 60 101. Fax. +43 1 60 101 1210 Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6, 220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773 Belgium: see The Netherlands Brazil: see South America Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor, 51 James Bourchier Blvd., 1407 SOFIA, Tel. +359 2 689 211, Fax. +359 2 689 102 Canada: PHILIPS SEMICONDUCTORS/COMPONENTS, Tel. +1 800 234 7381 China/Hong Kong: 501 Hong Kong Industrial Technology Centre, 72 Tat Chee Avenue, Kowloon Tong, HONG KONG, Tel. +852 2319 7888, Fax. +852 2319 7700 Colombia: see South America Czech Republic: see Austria Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S, Tel. +45 32 88 2636, Fax. +45 31 57 1949 Finland: Sinikalliontie 3, FIN-02630 ESPOO, Tel. +358 9 615800, Fax. +358 9 61580/xxx France: 4 Rue du Port-aux-Vins. BP317. 92156 SURESNES Cedex. Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427 Germany: Hammerbrookstraße 69, D-20097 HAMBURG, Tel. +49 40 23 53 60, Fax. +49 40 23 536 300 Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS, Tel. +30 1 4894 339/239, Fax. +30 1 4814 240 Hungary: see Austria India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd. Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722 Indonesia: see Singapore Ireland: Newstead, Clonskeagh, DUBLIN 14, Tel. +353 1 7640 000, Fax. +353 1 7640 200 Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007 Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3, 20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557 Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108, Tel. +81 3 3740 5130, Fax. +81 3 3740 5077 Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL, Tel. +82 2 709 1412, Fax. +82 2 709 1415 Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR, Tel. +60 3 750 5214, Fax. +60 3 757 4880 Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905, Tel. +9-5 800 234 7381 Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB, Tel. +31 40 27 82785, Fax. +31 40 27 88399 New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. +64 9 849 4160, Fax. +64 9 849 7811 Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000. Fax. +47 22 74 8341 Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474 Poland: UI. Lukiska 10, PL 04-123 WARSZAWA, Tel. +48 22 612 2831, Fax. +48 22 612 2327 Portugal: see Spain Romania: see Italy Russia: Philips Russia, UI. Usatcheva 35A, 119048 MOSCOW, Tel. +7 095 755 6918, Fax. +7 095 755 6919 Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231, Tel. +65 350 2538, Fax. +65 251 6500 Slovakia: see Austria Slovenia: see Italv South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale, 2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000, Tel. +27 11 470 5911, Fax. +27 11 470 5494 South America: Rua do Rocio 220, 5th floor, Suite 51, 04552-903 São Paulo, SÃO PAULO - SP, Brazil, Tel. +55 11 821 2333, Fax. +55 11 829 1849 Spain: Balmes 22, 08007 BARCELONA Tel. +34 3 301 6312, Fax. +34 3 301 4107 Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM, Tel. +46 8 632 2000, Fax. +46 8 632 2745 Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH, Tel. +41 1 488 2686, Fax. +41 1 481 7730 Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1, TAIPEI, Taiwan Tel. +886 2 2134 2870, Fax. +886 2 2134 2874 Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd. 209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260, Tel. +66 2 745 4090, Fax. +66 2 398 0793 Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL, Tel. +90 212 279 2770, Fax. +90 212 282 6707 Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7, 252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461 United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Haves. MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421 United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409, Tel. +1 800 234 7381 Uruguay: see South America

Vietnam: see Singapore Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD, Tel. +381 11 625 344, Fax.+381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

© Philips Electronics N.V. 1997

SCA53

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

547027/1200/01/pp20

Date of release: 1997 Feb 20

Document order number: 9397 750 01725

Let's make things better.

Internet: http://www.semiconductors.philips.com



